

Docket No.: M4065.0227/P227

Micron No.: 96-1123

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled:

METHOD AND APPARATUS FOR REDUCING SUBSTRATE BIAS VOLTAGE DROP

The specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by an amendment, if any, specifically referred to in this oath or declaration.

I acknowledge the duty to disclose all information known to me which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code §119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

NONE

I hereby claim the benefit under Title 35, United States Code, § 120/365 of any United States and PCT international application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56(a) which became available between the filing date of the prior application and the national or PCT international filing date of this application:

NONE

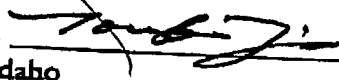
Docket No.: M4065.0227/P227
Micron No.: 96-1123

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Please address all correspondence to Thomas J. D'Amico of Dickstein Shapiro Morin & Oshinsky LLP located at 2101 L Street NW

Washington, DC 20037-1526. Telephone calls should be made to (202) 785-9700.

Full name of first inventor: Tongbi Jiang

Inventor's signature: 

Date:

8-29-00

Residence: Boise, Idaho

Citizenship: United States of America

Post Office Address: 12036 W. Patrina Drive
Boise, ID 83713

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Micron No.: 96-1123

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
DECLARATION FOR PATENT APPLICATION

Signature Page for Second Inventor

Full name of second inventor: Zhiqiang Wu

Inventor's signature: _____

Date: _____

Residence: Plano, Texas

Citizenship: United States of America

Post Office Address: 4012 Mildenhall Drive
Plano, Texas 75093

Docket No.: M4065.0227/P127

Micron No.: 96-1123

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**METHOD AND APPARATUS FOR REDUCING SUBSTRATE
BIAS VOLTAGE DROP**

The specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by an amendment, if any, specifically referred to in this oath or declaration.

I acknowledge the duty to disclose all information known to me which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code §119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

NONE

I hereby claim the benefit under Title 35, United States Code, § 120/365 of any United States and PCT international application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56(a) which became available between the filing date of the prior application and the national or PCT international filing date of this application:

NONE

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Micron No.: 96-1123

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Please address all correspondence to Thomas J. D'Amico of Dickstein Shapiro Morin & Oshinsky LLP located at 2101 L Street NW

Washington, DC 20037-1526. Telephone calls should be made to (202) 785-9700.

Full name of first inventor: Tongbi Jiang

Inventor's signature: _____

Date: _____

Residence: Boise, Idaho

Citizenship: China

Post Office Address: 12036 W. Patina Drive
Boise, ID 83713

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Docket No.: M4065.0227/P227
Micro No.: 96-1128

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

DECLARATION FOR PATENT APPLICATION

Signature Page for Second Inventor

Full name of second inventor: Zhiqiang Wu

Inventor's signature: 

Date: 08/28/00

Residence: Plano, Texas

Citizenship: United States of America

Post Office Address: 4012 Mildenhall Drive
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